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**Standardizacija toplotnih lastnosti pri polprevodniških ohišjih - 3. del: Simulacijski modeli toplotnih vezij diskretnih polprevodniških ohišij za prehodno analizo (IEC 63378-3:2025)**

Thermal standardization on semiconductor packages - Part 3: Thermal circuit simulation models of discrete semiconductor packages for transient analysis (IEC 63378-3:2025)

Thermische Standardisierung von Halbleitergehäusen - Teil 3: Thermische Schaltungssimulationsmodelle von diskreten Halbleitergehäusen für die Transientenanalyse (IEC 63378-3:2025)

Normalisation thermique des boîtiers de semiconducteurs - Partie 3: Modèles de simulation de circuits thermiques de boîtiers de semiconducteurs discrets pour analyse transitoire (IEC 63378-3:2025)

**Ta slovenski standard je istoveten z: EN IEC 63378-3:2025**

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**ICS:**

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
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**SIST EN IEC 63378-3:2025**

**en**

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EUROPEAN STANDARD  
NORME EUROPÉENNE  
EUROPÄISCHE NORM

**EN IEC 63378-3**

June 2025

ICS 31.080.01

English Version

**Thermal standardization on semiconductor packages - Part 3:  
Thermal circuit simulation models of discrete semiconductor  
packages for transient analysis  
(IEC 63378-3:2025)**

Normalisation thermique des boîtiers de semiconducteurs -  
Partie 3: Modèles de simulation de circuits thermiques de  
boîtiers de semiconducteurs discrets pour analyse  
transitoire  
(IEC 63378-3:2025)

Thermische Standardisierung von Halbleitergehäusen - Teil  
3: Thermische Schaltungssimulationsmodelle von diskreten  
Halbleitergehäusen für die Transientenanalyse  
(IEC 63378-3:2025)

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## EN IEC 63378-3:2025 (E)

### European foreword

The text of document 47D/967/CDV, future edition 1 of IEC 63378-3, prepared by SC 47D "Semiconductor devices packaging" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 63378-3:2025.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2026-06-30 level by publication of an identical national standard or by endorsement
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# INTERNATIONAL STANDARD

## NORME INTERNATIONALE

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**Thermal standardization on semiconductor packages –  
Part 3: Thermal circuit simulation models of discrete semiconductor packages  
for transient analysis**

**Normalisation thermique des boîtiers de semi-conducteurs –  
Partie 3: Modèles de simulation de circuits thermiques de boîtiers de  
semi-conducteurs discrets pour analyse transitoire**